

Applicant(s)	John T. Gasner	<p style="text-align: center;">INFORMATION DISCLOSURE STATEMENT</p>
Serial No.	Unassigned	
Filing Date	Herewith	
Group Art Unit	Unknown	
Examiner	Unknown	
Attorney Docket No.	125.090US01	
<p>Title: ACTIVE AREA BONDING COMPATIBLE HIGH CURRENT STRUCTURES</p>		

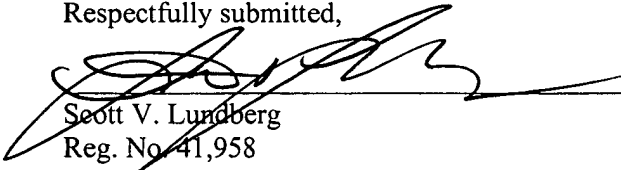
Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with 37 C.F.R. §§ 1.56 and 1.97, *et seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified Application. Applicant respectfully requests that this Information Disclosure Statement be entered and the references listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to MPEP §609, Applicant further requests that the Examiner initial next to each reference on the Form 1449 to indicate that the listed references have been considered. Applicant further requests that a copy of the initialed Form 1449 be returned with the next official communication.

The Examiner is invited to contact the Applicant's Representative at the below-listed telephone number if there are any questions regarding this communication.

Date: 10-31-03

Respectfully submitted,


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Applicant(s)	John T. Gasner et al.	INFORMATION DISCLOSURE STATEMENT FORM PTO-1449
Serial No.	Unassigned	
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Examiner Name	Unassigned	
Attorney Docket No.	125.090US01	
Title: ACTIVE AREA BONDING COMPATIBLE HIGH CURRENT STRUCTURES		Sheet 1 of 1

U.S. Patent References				
Examiner Initials	Patent No.	Issue Date	Name	Filing Date
	4,695,868	09/22/87	Fisher	12/13/85

Foreign Patent References					
Examiner Initials	Foreign Patent		Name	Publication Date	T
	Country	No.			
	NONE				

Other References	
Examiner Initials	Author, Title, Date, Pages, etc.
	W. R. Anderson et al, "ESD Protection Under Wire Bonding Pads", EOS/ESD Symposium, 1999, pgs. 2A4.1-2A4.7.
	W. R. Anderson et al., "Reliability considerations for ESD protection under wire bonding pads", Microelectronics Reliability 41 (2001) pgs. 367-373.
	T. B. Ching et al., "Bond Pad Structure Reliability", Texas Instruments Incorporated, 1998 IEEE, pgs. 64-70

Examiner Signature		Date Considered	
*Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.			